2,097,152-word \times 8-bit Dynamic RAM

HITACHI

ADE-203-664C (Z) Rev. 3.0 Feb. 24, 1997

Description

The Hitachi HM51W17800 is a CMOS dynamic RAM organized 2,097,152-word × 8-bit. It employs the most advanced CMOS technology for high performance and low power. The HM51W17800 offers Fast Page Mode as a high speed access mode. Multiplexed address input permits the HM51W17800 to be packaged in standard 28-pin plastic SOJ and 28-pin TSOP.

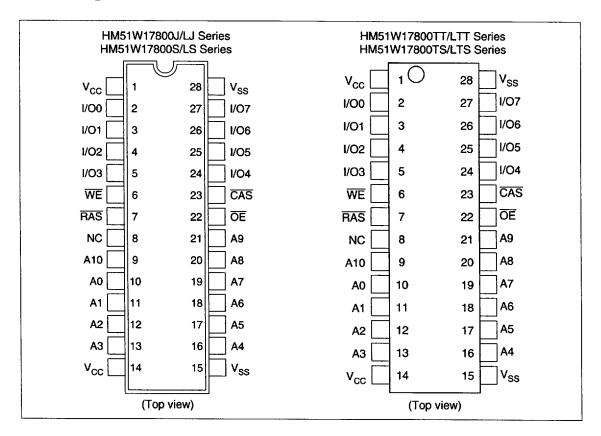
Features

- Single 3.3 V (±0.3 V)
- Access time: 50 ns/60 ns/70 ns (max)
- Power dissipation
 - Active mode: 396 mW/360 mW/324 mW (max)
 - Standby mode
 - 7.2 mW (max)
 - 0.54 mW (max) (L-version)
- · Fast page mode capability
- · Refresh cycles
 - 2048 refresh cycles
 - 32 ms
 - 128 ms (L-version)
- 4 variations of refresh
 - RAS-only refresh
 - CAS-before-RAS refresh
 - Hidden refresh
 - Self refresh (L-version)
- Battery backup operation (L-version)

Ordering Information

Type No.	Access time	Package
HM51W17800J-5	50 ns	400-mil 28-pin plastic SOJ (CP-28DA)
HM51W17800J-6	60 ns	, , , , , , , , , , , , , , , , , , , ,
HM51W17800J-7	70 ns	
HM51W17800LJ-5	50 ns	400-mil 28-pin plastic SOJ (CP-28DA)
HM51W17800LJ -6	60 ns	, , , , , , , , , , , , , , , , , , , ,
HM51W17800LJ -7	70 ns	
HM51W17800S-5	50 ns	300-mil 28-pin plastic SOJ (CP-28DNA)
HM51W17800S-6	60 ns	(=======,
HM51W17800S-7	70 ns	
HM51W17800LS-5	50 ns	300-mil 28-pin plastic SOJ (CP-28DNA)
HM51W17800LS-6	60 ns	,
HM51W17800LS-7	70 ns	
HM51W17800TT-5	50 ns	400-mil 28-pin plastic TSOP II (TTP-28DA)
HM51W17800TT-6	60 ns	. , , , , , , , , , , , , , , , , , , ,
HM51W17800TT-7	70 ns	
HM51W17800LTT-5	50 ns	400-mil 28-pin plastic TSOP II (TTP-28DA)
HM51W17800LTT-6	60 ns	, , , , , , , , , , , , , , , , , , , ,
HM51W17800LTT-7	70 ns	
HM51W17800TS-5	50 ns	300-mil 28-pin plastic TSOP II (TTP-28DB)
HM51W17800TS-6	60 ns	, , ==== , , , , ====,
HM51W17800TS-7	70 ns	
HM51W17800LTS-5	50 ns	300-mil 28-pin plastic TSOP II (TTP-28DB)
HM51W17800LTS-6	60 ns	, , , , , , , , , , , , , , , , , , , ,
HM51W17800LTS-7	70 ns	

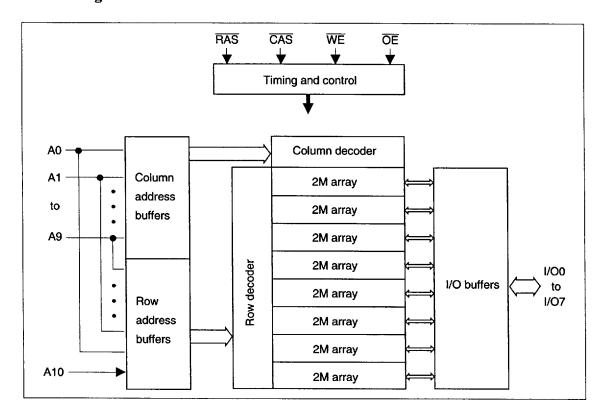
Pin Arrangement



Pin Description

Pin name	Function	
A0 to A10	Address input	
	Row/Refresh address A0 to A10	
	Column address A0 to A9	
I/O0 to I/O7	Data input/data output	
RAS	Row address strobe	
CAS	Column address strobe	
WE	Read/Write enable	
ŌĒ	Output enable	
V _{cc}	Power supply	
V _{ss}	Ground	
NC	No connection	

Block Diagram



Absolute Maximum Ratings

Parameter	Symbol	Value	Unit V		
Voltage on any pin relative to V _{ss}	V _T	-0.5 to + 4.6			
Supply voltage relative to V_{ss} V_{cc} Short circuit output current lout Power dissipation P_{τ}		-0.5 to + 4.6	V		
		50	mA		
		1.0	W		
Operating temperature	Topr	0 to +70	°C		
Storage temperature	Tstg	-55 to +125	°C		

Recommended DC Operating Conditions (Ta = $0 \text{ to } +70^{\circ}\text{C}$)

Parameter	Symbol	Min	Тур	Max	Unit	Notes	
Supply voltage	V _{cc}	3.0	3.3	3.6	٧	1, 2	
Input high voltage	V _{iH}	2.0	_	V _{cc} + 0.3	٧	1	
Input low voltage	V _{iL}	-0.3	_	0.8	٧	1	

Notes: 1. All voltage referred to V_{ss}

DC Characteristics (Ta = 0 to +70°C, V_{cc} = 3.3 V \pm 0.3 V, V_{ss} = 0 V)

HM51W17800

		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Test conditions
Operating current*1, *2	I _{cc1}	_	110	_	100	_	90	mA	t _{RC} = min
Standby current	I _{CC2}	_	2	_	2	_	2	mA	TTL interface RAS, CAS = V _{IH} Dout = High-Z
Standby current		_	1	_	1	_	1	mA	CMOS interface RAS, CAS ≥ V _{cc} – 0.2V Dout = High-Z
Standby current (L-version)	I _{CC2}	_	150	_	150	_	150	μА	CMOS interface RAS, CAS ≥ V _{cc} – 0.2V Dout = High-Z
RAS-only refresh current*2	I _{ccs}	_	110		100		90	mA	t _{RC} = min
Standby current*1	I _{CC5}	_	5	_	5	_	5	mA	RAS = V _{IH} CAS = V _{IL} Dout = enable
CAS-before-RAS refresh current	I _{CC6}	_ "	110	_	100	_	90	mA	t _{RC} = min
Fast page mode current*1. *3	I _{CC7}		100	_	90	_	85	mA	t _{PC} = min
Battery backup current*4 (Standby with CBR refresh) (L-version)	I _{CC10}	_	400	_	400	_	400	μА	CMOS interface Dout = High-Z CBR refresh: t_{RC} = 62.5 μ s $t_{RAS} \le 0.3 \ \mu$ s
Self refresh mode current (L-version)	I _{CC11}		250	_	250	_	250	μΑ	CMOS interface RAS, CAS ≤ 0.2V Dout = High-Z
Input leakage current	l _u	-10	10	-10	10	-10	10	μА	0 V ≤ Vin ≤ 4.6 V
Output leakage current	I _{LO}	-10	10	-10	10	-10	10	μА	0 V ≤ Vout ≤ 4.6 V Dout = disable
Output high voltage	V _{OH}	2.4	V _{cc}	2.4	V _{cc}	2.4	V _{cc}	٧	High lout = -2 mA
Output low voltage	V _{OL}	0	0.4	0	0.4	0	0.4	٧	Low lout = 2 mA

Notes: 1. I_{cc} depends on output load condition when the device is selected. I_{cc} max is specified at the output open condition.

^{2.} Address can be changed once or less while $\overline{RAS} = V_{ii}$.

^{3.} Address can be changed once or less while $\overline{CAS} = V_{H}$.

^{4.} $\overline{CAS} = L (\le 0.2 \text{ V}) \text{ while } \overline{RAS} = L (\le 0.2 \text{ V}).$

Capacitance (Ta = 25°C, V_{CC} = 3.3 V \pm 0.3 V)

Parameter	Symbol	Тур	Max	Unit	Notes
Input capacitance (Address)	C _{II}	_	5	ρF	1
Input capacitance (Clocks)	Cls	_	7	pF	1
Output capacitance (Data-in, Data-out)	C _{vo}	_	7	pF	1, 2

Notes: 1. Capacitance measured with Boonton Meter or effective capacitance measuring method.

2. $\overline{CAS} = V_{H}$ to disable Dout.

AC Characteristics (Ta = 0 to +70°C, V_{cc} = 3.3 V \pm 0.3 V, V_{ss} = 0 V)*1, *2, *18

Test Conditions

• Input rise and fall time: 5 ns

Input timing reference levels: 0.8 V, 2.0 V
Output timing reference levels: 0.8 V, 2.0 V

• Output load: 1 TTL gate + C_L (100 pF) (Including scope and jig)

 $\textbf{Read, Write, Read-Modify-Write and Refresh Cycles} \ (Common \ parameters)$

HM51W17800

	-5		-6		-7		•			
Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes		
t _{RC}	90		110	_	130	_	ns	1.4.		
t _{RP}	30	_	40	_	50	_	ns			
t _{CP}	8	_	10	_	10		ns			
t _{RAS}	50	10000	60	10000	70	10000	ns			
t _{CAS}	13	10000	15	10000	18	10000	ns			
t _{ASR}	0	_	0	_	0	_	ns			
t _{rah}	8	_	10	_	10	_	ns			
t _{ASC}	0	_	0	_	0	_	ns			
t _{CAH}	8	_	10	_	15	_	ns			
t _{RCD}	18	37	20	45	20	52	ns	3		
t _{RAD}	13	25	15	30	15	35	ns	4		
t _{ash}	13	_	15		18	_	ns			
t _{сsн}	50		60	_	70	_	ns			
t _{CRP}	5	_	5		5	_	ns			
toed	13	_	15		18		ns	5		
t _{DZO}	0	_	0		0	_	ns	6		
t _{DZC}	0	_	0	_	0		ns	6		
t _r	3	50	3	50	3	50	ns	7		
	trick	Symbol Min t _{RC} 90 t _{RP} 30 t _{CP} 8 t _{RAS} 50 t _{CAS} 13 t _{ASR} 0 t _{RAH} 8 t _{CAH} 8 t _{RCD} 18 t _{RAD} 13 t _{RSH} 13 t _{CSH} 50 t _{CGRP} 5 t _{OED} 13 t _{DZO} 0 t _{DZC} 0	Symbol Min Max t _{RC} 90 — t _{RP} 30 — t _{CP} 8 — t _{RAS} 50 10000 t _{CAS} 13 10000 t _{ASR} 0 — t _{RAH} 8 — t _{CAH} 8 — t _{CAH} 8 — t _{RCD} 18 37 t _{RAD} 13 25 t _{RSH} 13 — t _{CSH} 50 — t _{CERP} 5 — t _{OED} 13 — t _{DZO} 0 —	Symbol Min Max Min t _{RC} 90 — 110 t _{RP} 30 — 40 t _{CP} 8 — 10 t _{RAS} 50 10000 60 t _{CAS} 13 10000 15 t _{ASR} 0 — 0 t _{RAH} 8 — 10 t _{CAH} 8 — 10 t _{RCD} 18 37 20 t _{RAD} 13 25 15 t _{CSH} 50 — 60 t _{CSH} 5 — 5 t _{OED} 13 — 15 t _{DZC} 0 — 0	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Symbol Min Max Min Max Min Max Min Max t _{RC} 90 — 110 — 130 — t _{RP} 30 — 40 — 50 — t _{CP} 8 — 10 — 10 — t _{RAS} 50 10000 60 10000 70 10000 t _{CAS} 13 10000 15 10000 18 10000 t _{ASR} 0 — 0 — 0 — t _{ASR} 0 — 0 — 0 — t _{CAS} 13 10000 15 10000 18 10000 t _{CAS} 0 — 0 — 0 — t _{CAS} 18 — 10 — 15 — t _{CAH} 8 — 10 — 15 — t _{RAD} 13 </td <td>$\begin{array}{c ccccccccccccccccccccccccccccccccccc$</td>	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		

Read Cycle

HM	E 4	11/4	70	$\Delta \Delta$
пм	IJΙ	7V I	70	w

							-		
	-5		-6		-7		_		
Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes	
t _{RAC}	_	50	_	60	_	70	ns	8, 9	
t _{CAC}		13	_	15		18	ns	9, 10, 17,	
t _{AA}		25	_	30		35	ns	9, 11, 17,	
t _{OEA}		13	_	15	_	18	ns	9	
t _{RCS}	0	_	0	_	0	_	ns		
t _{RCH}	0	_	0	_	0		ns	12	
t _{RRH}	0	_	0		0		ns	12	
t _{RAL}	25	_	30	_	35	_	ns		
t _{CAL}	25	_	30		35	-	ns		
t _{cLZ}	0	_	0	_	0	_	ns		
t _{on}	3	_	3		3	_	ns		
t _{oHO}	3	_	3	_	3	_	ns		
toff		13	_	15		15	ns	13	
t _{oez}	_	13		15		15	ns	13	
t _{CDD}	13	_	15	_	18		ns	5	
	trac tcac tcac ttaa toea tres tres tres tres tres tres tres tres	trac — tcac — tcac — taa — toea — tres 0 tres 0	Symbol Min Max t _{RAC} — 50 t _{CAC} — 13 t _{AA} — 25 t _{OEA} — 13 t _{RCS} 0 — t _{RCH} 0 — t _{RRH} 25 — t _{CAL} 25 — t _{OH} 3 — t _{OHO} 3 — t _{OFF} — 13 t _{OEZ} — 13	Symbol Min Max Min t _{RAC} — 50 — t _{CAC} — 13 — t _{AA} — 25 — t _{OEA} — 13 — t _{RCS} 0 — 0 t _{RCH} 0 — 0 t _{RRH} 0 — 0 t _{CAL} 25 — 30 t _{CLZ} 0 — 0 t _{OH} 3 — 3 t _{OHO} 3 — 3 t _{OFF} — 13 — t _{OEZ} — 13 —	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Symbol Min Max Min Max Min Max Min Max t _{RAC} — 50 — 60 — 70 t _{CAC} — 13 — 15 — 18 t _{AA} — 25 — 30 — 35 t _{OEA} — 13 — 15 — 18 t _{RCS} 0 — 0 — 0 — t _{RCS} 0 — 0 — 0 — t _{RCH} 0 — 0 — 0 — t _{RRH} 0 — 30 — 35 — t _{CAL} 25 — 30 — 35 — t _{CAL} 25 — 30 — 35 — t _{CAL} 3 — 3 — 3 — t _{CAL} 3 — 3 <td>$\begin{array}{c ccccccccccccccccccccccccccccccccccc$</td>	$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	

Write Cycle

HM51W17800

	Symbol	-5		-6		-7			
Parameter		Min	Max	Min	Max	Min	Max	Unit	Notes
Write command setup time	t _{wcs}	0	_	0		0	_	ns	14
Write command hold time	t _{wcH}	8		10	_	15	_	ns	
Write command pulse width	t _{we}	8		10		10		ns	
Write command to RAS lead time	t _{RWL}	13	_	15	_	18	_	ns	-
Write command to CAS lead time	t _{cwL}	13	_	15	_	18		ns	-
Data-in setup time	tos	0		0	_	0	_	ns	15
Data-in hold time	t _{DH}	8	_	10	_	15		ns	15

Read-Modify-Write Cycle

HM51W17800

		-5		-6		-7		_	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	 Unit	Notes
Read-modify-write cycle time	t _{nwc}	131	_	155	_	181		ns	
RAS to WE delay time	t _{RWD}	73	_	85	_	98	_	ns	14
CAS to WE delay time	t _{cwp}	36	_	40		46		ns	14
Column address to WE delay time	t _{AWD}	48	_	55	-	63		ns	14
OE hold time from WE	t _{OEH}	13		15		18		ns	

Refresh Cycle

HM51W17800

		-5		-6		-7		-	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
CAS setup time (CBR refresh cycle)	t _{CSR}	5	_	5		5	_	ns	
CAS hold time (CBR refresh cycle)	t _{CHR}	8	_	10	_	10	_	ns	
WE setup time (CBR refresh cycle)	twee	0	_	0		0	_	ns	
WE hold time (CBR refresh cycle)	t _{wrt}	8	_	10	_	10	_	ns	
RAS precharge to CAS hold time	t _{RPC}	5		5	_	5		ns	

Fast Page Mode Cycle

HM51W17800

		-5		-6		-7			
Parameter	Symbol	Min	Max	Min	Max	Min	Max	Unit	Notes
Fast page mode cycle time	t _{PC}	35	_	40	-	45	_	ns	
Fast page mode RAS pulse width	t _{rasp}	_	100000		100000		100000	ns	16
Access time from CAS precharge	t _{CPA}		30		35	_	40	ns	9, 17
RAS hold time from CAS precharge	t _{CPRH}	30	_	35		40		ns	

Fast Page Mode Read-Modify-Write Cycle

HM51W17800

		-5		-6		-7		-	
Parameter	Symbol	Min	Max	Min	Max	Min	Max	- Unit	Notes
Fast page mode read-modify- write cycle time	t _{PRWC}	76		85	<u></u>	96		ns	
WE delay time from CAS precharge	t _{CPW}	53		60	_	68	_	ns	14

Refresh

Parameter	Symbol	Max	Unit	Note
Refresh period	t _{REF}	32	ms	2048 cycles
Refresh period (L-version)	t _{REF}	128	ms	2048 cycles

Self Refresh Mode (L-version)

HM51W17800L

		-5	-	-6 Min	Max	-7 Min	Max	- Unit	
Parameter	Symbol	Min	Max						Notes
RAS pulse width (self refresh)	t _{RASS}	100	_	100		100		μs	19, 20, 21, 22
RAS precharge time (self refresh)	t _{RPS}	90	_	110		130		ns	
CAS hold time (self refresh)	t _{chs}	-50		-50	_	-50	_	ns	

Notes: 1. AC measurements assume $t_r = 5$ ns.

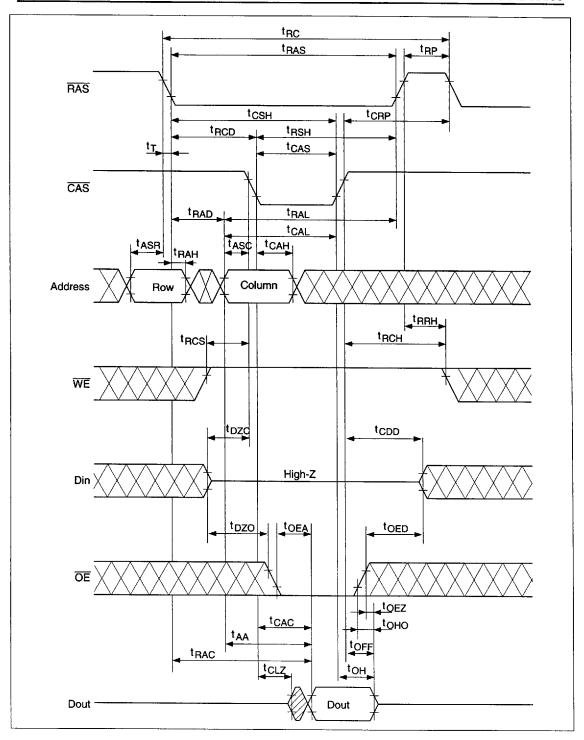
- An initial pause of 200 µs is required after power up followed by a minimum of eight initialization cycles (any combination of cycles containing RAS-only refresh or CAS-before-RAS refresh). If the internal refresh counter is used, a minimum of eight CAS-before-RAS refresh cycles are required.
- Operation with the t_{RCD} (max) limit insures that t_{RAC} (max) can be met, t_{RCD} (max) is specified as a reference point only; if t_{RCD} is greater than the specified t_{RCD} (max) limit, then access time is controlled exclusively by t_{CAC}.
- 4. Operation with the t_{RAD} (max) limit insures that t_{RAD} (max) can be met, t_{RAD} (max) is specified as a reference point only; if t_{RAD} is greater than the specified t_{RAD} (max) limit, then access time is controlled exclusively by t_{AA}.
- 5. Either toen or ton must be satisfied.
- Either t_{DZO} or t_{DZC} must be satisfied.
- V_{IH} (min) and V_{IL} (max) are reference levels for measuring timing of input signals. Also, transition times are measured between V_{IH} (min) and V_{IL} (max).
- 8. Assumes that $t_{RCD} \le t_{RCD}$ (max) and $t_{RAD} \le t_{RAD}$ (max). If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} exceeds the value shown.
- Measured with a load circuit equivalent to 1 TTL loads and 100 pF. (V_{OH} = 2.0 V, V_{OI} = 0.8 V)
- 10. Assumes that $t_{\text{RCD}} \ge t_{\text{RCD}}$ (max) and $t_{\text{RAD}} \le t_{\text{RAD}}$ (max).
- 11. Assumes that $t_{RCD} \le t_{RCD}$ (max) and $t_{RAD} \ge t_{RAD}$ (max).
- 12. Either t_{RCH} or t_{RRH} must be satisfied for a read cycles.
- 13. t_{OFF} (max) and t_{OEZ} (max) define the time at which the outputs achieve the open circuit condition and are not referred to output voltage levels.
- 14. t_{WCS}, t_{RWD}, t_{CWD}, t_{AWD} and t_{CPW} are not restrictive operating parameters. They are included in the data sheet as electrical characteristics only; if t_{WCS} ≥ t_{WCS} (min), the cycle is an early write cycle and the data out pin will remain open circuit (high impedance) throughout the entire cycle; if t_{RWD} ≥ t_{RWD} (min), t_{CWD} ≥ t_{CWD} (min), and t_{AWD} ≥ t_{AWD} (min), or t_{CWD} ≥ t_{CWD} (min), the cycle is a read-modify-write and the data output will contain data read from the selected cell; if neither of the above sets of conditions is satisfied, the condition of the data out (at access time) is indeterminate.
- 15. These parameters are referred to CAS leading edge in early write cycles and to WE leading edge in delayed write or read-modify-write cycles.
- 16. t_{BASP} defines RAS pulse width in Fast page mode cycles.
- 17. Access time is determined by the longest among $t_{\text{AA}},\,t_{\text{CAC}}$ and t_{CPA}
- 18. In delayed write or read-modify-write cycles, OE must disable output buffer prior to applying data to the device.
- 19. Please do not use t_{RASS} timing, 10 μ s $\leq t_{RASS} \leq$ 100 μ s. During this period, the device is in transition state from normal operation mode to self refresh mode. If $t_{RASS} \geq$ 100 μ s, then \overline{RAS} precharge time should use t_{RPS} instaed of t_{RP} .

- 20. If you use RAS only refresh or CBR burst refresh mode in normal read/write cycles, 2048 cycles of distributed CBR refresh with 15.6 μs interval should be executed within 32 ms immediately after exiting from and before entering into the self refresh mode.
- 21. If you use distributed CBR refresh mode with 15.6 μs interval in normal read/write cycle, CBR refresh should be executed within 15.6 μs immediately after exiting from and before entering into self refresh mode.
- 22. Repetitive self refresh mode without refreshing all memory is not allowed. Once you exit from self refresh mode, all memory cells need to be refreshed before re-entering the self refresh mode again.
- 23. XXX: H or L (H: V_{iH} (min) $\leq V_{iN} \leq V_{iH}$ (max), L: V_{iL} (min) $\leq V_{iN} \leq V_{iL}$ (max)) //////: Invalid Dout

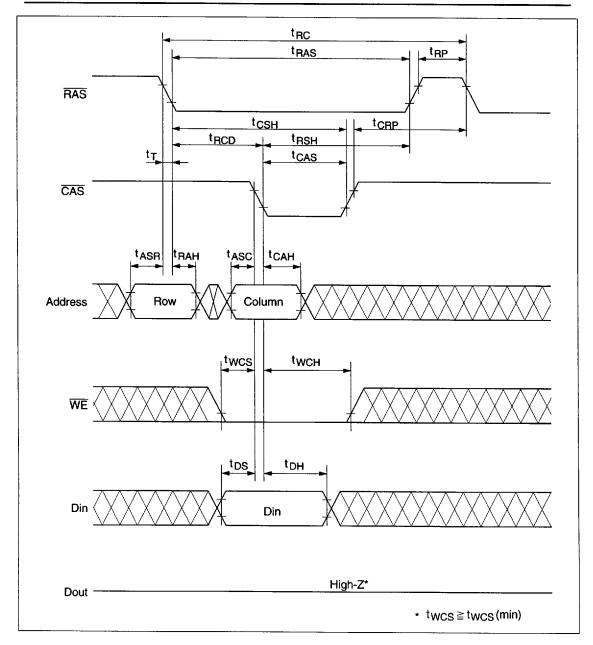
When the address, clock and input pins are not described on timing waveforms, their pins must be applied V_{IH} or V_{IL} .

Timing Waveforms*23

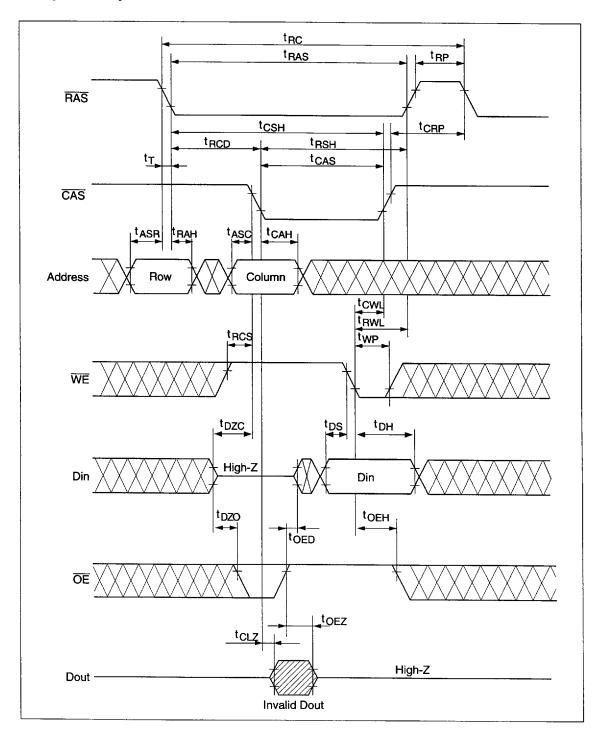
Read Cycle



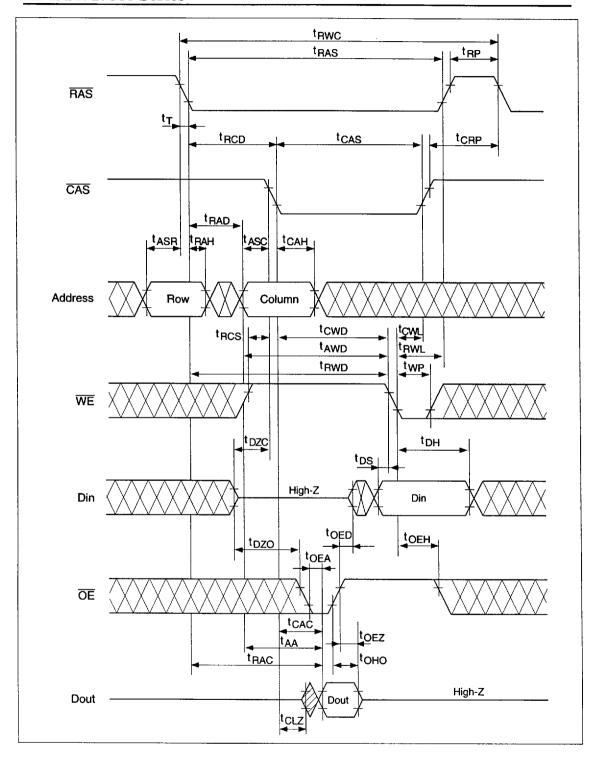
Early Write Cycle



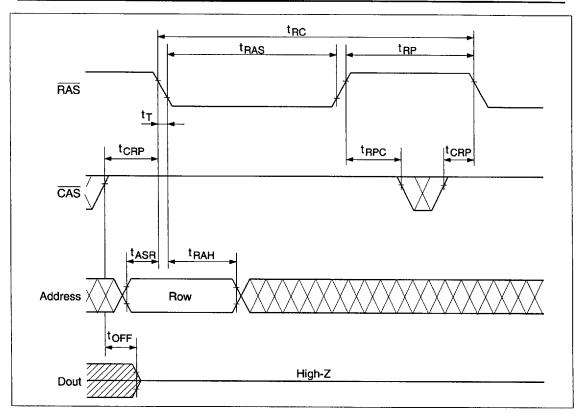
Delayed Write Cycle*18



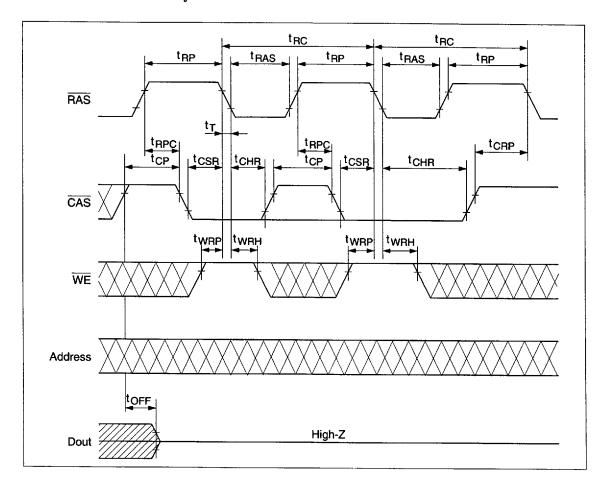
Read-Modify-Write Cycle*18



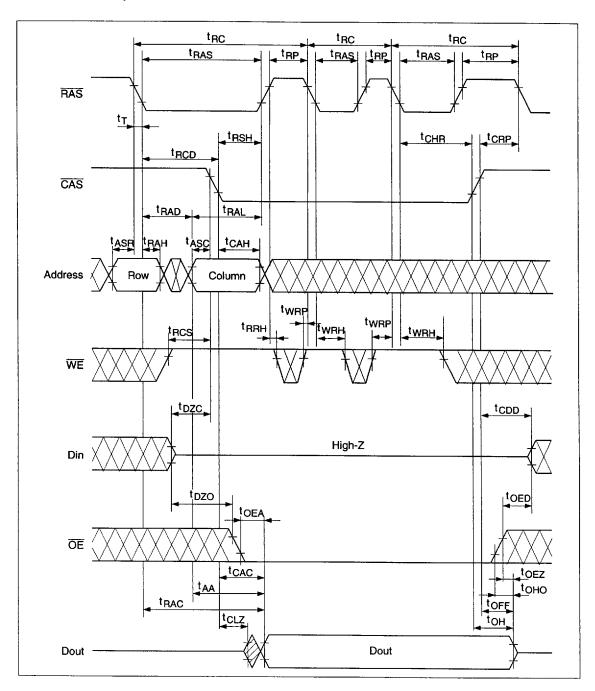
RAS-Only Refresh Cycle



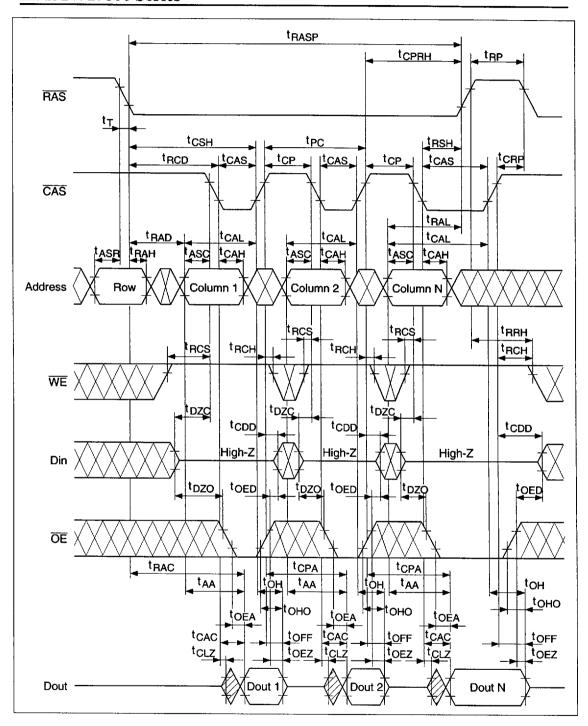
$\overline{\text{CAS}}\text{-Before-}\overline{\text{RAS}}$ Refresh Cycle



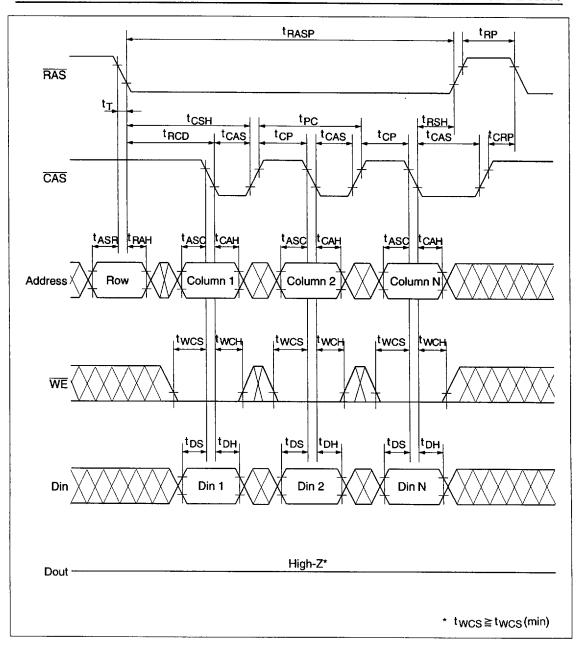
Hidden Refresh Cycle



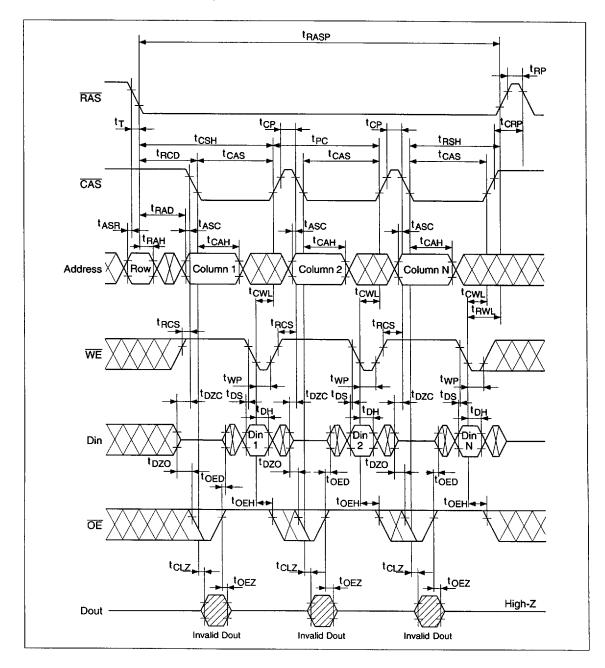
Fast Page Mode Read Cycle



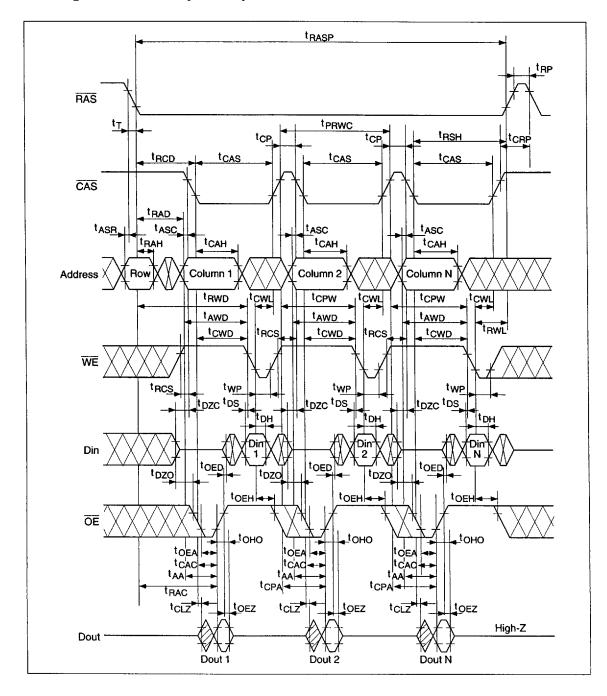
Fast Page Mode Early Write Cycle



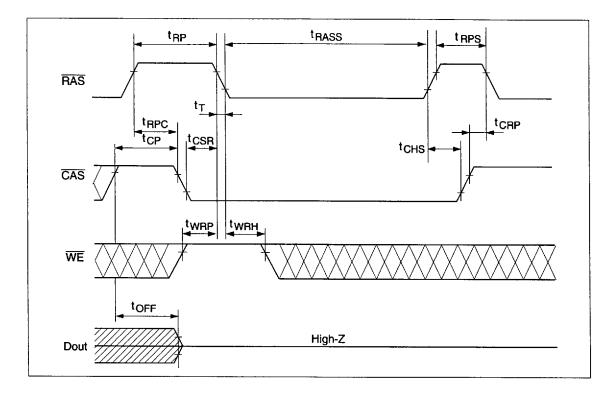
Fast Page Mode Delayed Write Cycle*18



Fast Page Mode Read-Modify-Write Cycle*18

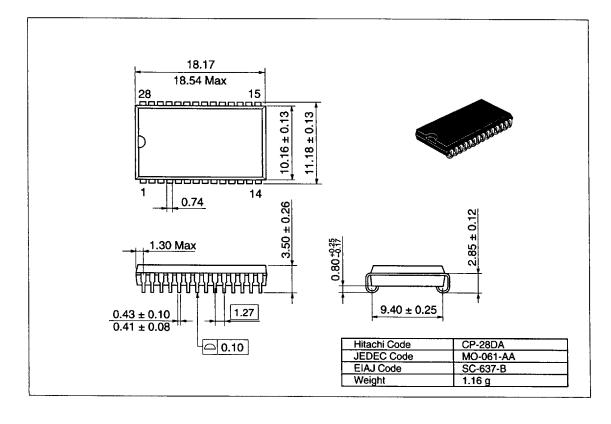


Self Refresh Cycle (L-version)*19, *20, *21, *22

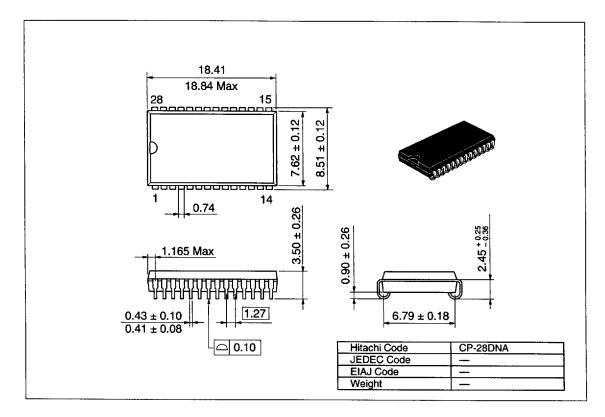


Package Dimensions

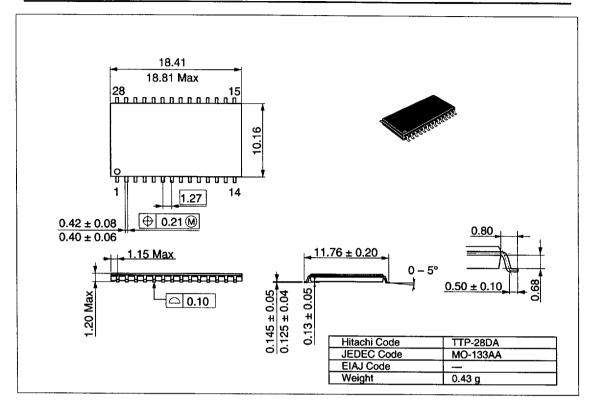
HM51W17800J/LJ Series (CP-28DA)



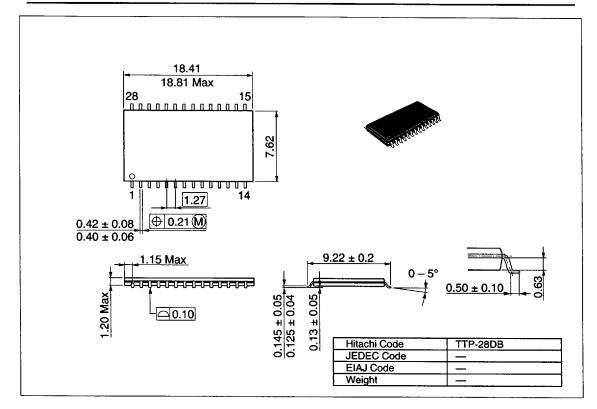
HM51W17800S/LS Series (CP-28DNA)



HM51W17800TT/LTT Series (TTP-28DA)



HM51W17800TS/LTS Series (TTP-28DB)



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Revision Record

Rev.	Date	Contents of Modification	Drawn by	Approved by
1.0	Sep. 30, 1996	Initial issue	Y. Kasama	M. Mishima
2.0	Dec. 5, 1996	Addition of HM51W17800-5 Series	Y. Kasama	M. Mishima
		Addition of HM51W17800S/LS Series (CP-28DNA)		
		Addition of HM51W17800TS/LTS Series (TTP-28DB)	
		Power dissipation (active)		
		432/396 mW(max) to 396/360/324 mW (max)		
		DC Characteristics		
		I _{cc1} max: 120/110 mA to 110/100/90 mA I _{cc3} max: 120/110 mA to 110/100/90 mA I _{cc6} max: 120/110 mA to 110/100/90 mA I _{cc7} max: 100/90 mA to 100/90/85 mA		
		AC Characteristics		
		t_{RRH} min: 0/0 ns to 5/5/5 ns t_{RPC} min: 0/0 ns to 5/5/5 ns		
3.0	Feb. 24, 1997	AC Characteristics t _{RRH} min: 5/5/5 ns to 0/0/0 ns		